

**DECLARATION AND POWER OF ATTORNEY
FOR PATENT APPLICATION**

ATTORNEY DOCKET NO. 200312986-1

As a below named inventor, I hereby declare that:

My residence/post office address and citizenship are as stated below next to my name;

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled:

**SYSTEMS AND METHODS FOR FAULT-TOLERANT PROCESSING WITH PROCESSOR REGROUPING
BASED ON CONNECTIVITY CONDITIONS**

the specification of which is attached hereto unless the following box is checked:

() was filed on _____ as US Application No. or PCT International Application Number _____ and was amended on _____ (if applicable).

I hereby state that I have reviewed and understood the contents of the above-identified specification, including the claims, as amended by any amendment(s) referred to above. I acknowledge the duty to disclose all information which is material to patentability as defined in 37 CFR 1.56.

Foreign Application(s) and/or Claim of Foreign Priority

I hereby claim foreign priority benefits under Title 35, United States Code Section 119 of any foreign application(s) for patent or inventor(s) certificate listed below and have also identified below any foreign application for patent or inventor(s) certificate having a filing date before that of the application on which priority is claimed:

COUNTRY	APPLICATION NUMBER	DATE FILED	PRIORITY CLAIMED UNDER 35 U.S.C. 119
			YES: _____ NO: _____
			YES: _____ NO: _____

Provisional Application

I hereby claim the benefit under Title 35, United States Code Section 119(e) of any United States provisional application(s) listed below:

APPLICATION NUMBER	FILING DATE

U. S. Priority Claim

I hereby claim the benefit under Title 35, United States Code, Section 120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code Section 112, I acknowledge the duty to disclose material information as defined in Title 37, Code of Federal Regulations, Section 1.56(a) which occurred between the filing date of the prior application and the national or PCT international filing date of this application:

APPLICATION NUMBER	FILING DATE	STATUS (patented/pending/abandoned)

POWER OF ATTORNEY:

As a named inventor, I hereby appoint the following attorney(s) and/or agent(s) to prosecute this application and transact all business in the Patent and Trademark Office connected therewith:

Customer Number **022879**

0 2 2 8 7 9

Send Correspondence to:

HEWLETT-PACKARD COMPANY
Intellectual Property Administration
P.O. Box 272400
Fort Collins, Colorado 80527-2400

Direct Telephone Calls To:

Gerald Laws
(281) 518-7159

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Full Name of Inventor: Man-Ho Lawrence Lee Citizenship: Hong Kong

Residence: Milpitas, CA

Post Office Address: 747 Jennifer Way, Milpitas, CA 95035

[Signature]
Inventor's Signature

Jan 8th, 2004

Date

**DECLARATION AND POWER OF ATTORNEY
FOR PATENT APPLICATION (continued)**

ATTORNEY DOCKET NO. 200312986-1

Full Name of Joint Inventor: Kousik Bera Citizenship: Indian
Residence: India
Post Office Address: 11C/303 Spring Leaf Apt. Lokhandwala Township, Kandivali(E), Mumbai, Maharashtra 400101 INDIA
Kousik, Bera. Date: 12 TH JAN, 2004
Inventor's Signature _____

Full Name of Joint Inventor: Marcelo Moraes de Azevedo Citizenship: Brazilian
Residence: Round Rock, TX
Post Office Address: 8712 Tin Roof Cove, Round Rock, TX 78681
Inventor's Signature _____ Date _____

Full Name of Joint Inventor: _____ Citizenship: _____
Residence: _____
Post Office Address: _____
Inventor's Signature _____ Date _____

Full Name of Joint Inventor: _____ Citizenship: _____
Residence: _____
Post Office Address: _____
Inventor's Signature _____ Date _____

Full Name of Joint Inventor: _____ Citizenship: _____
Residence: _____
Post Office Address: _____
Inventor's Signature _____ Date _____

Full Name of Joint Inventor: _____ Citizenship: _____
Residence: _____
Post Office Address: _____
Inventor's Signature _____ Date _____

Full Name of Joint Inventor: _____ Citizenship: _____
Residence: _____
Post Office Address: _____
Inventor's Signature _____ Date _____

**DECLARATION AND POWER OF ATTORNEY
FOR PATENT APPLICATION (continued)**

ATTORNEY DOCKET NO. 200312986-1

Full Name of joint inventor: Kusik Bera Citizenship: Indian

Residence: India

Post Office Address: 11C/303 Spring Leaf Apt, Lokhandwala Township, Kandivali(E), Mumbai, Maharashtra 400101 INDIA

Inventor's Signature _____ Date _____

Full Name of joint inventor: Marcelo Moraes de Azevedo Citizenship: Brazilian

Residence: Round Rock, TX

Post Office Address: 8712 Tin Roof Cove, Round Rock, TX 78681

Marcelo Moraes de Azevedo Date January 8, 2004

Full Name of joint inventor: _____ Citizenship: _____

Residence: _____

Post Office Address: _____

Inventor's Signature _____ Date _____

Full Name of joint inventor: _____ Citizenship: _____

Residence: _____

Post Office Address: _____

Inventor's Signature _____ Date _____

Full Name of joint inventor: _____ Citizenship: _____

Residence: _____

Post Office Address: _____

Inventor's Signature _____ Date _____

Full Name of joint inventor: _____ Citizenship: _____

Residence: _____

Post Office Address: _____

Inventor's Signature _____ Date _____

Full Name of joint inventor: _____ Citizenship: _____

Residence: _____

Post Office Address: _____

Inventor's Signature _____ Date _____